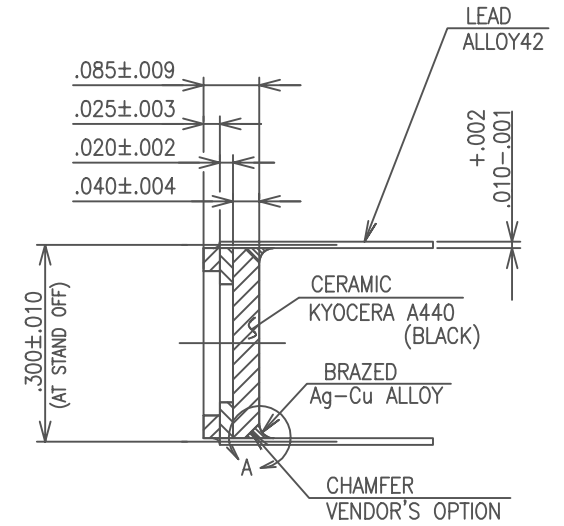
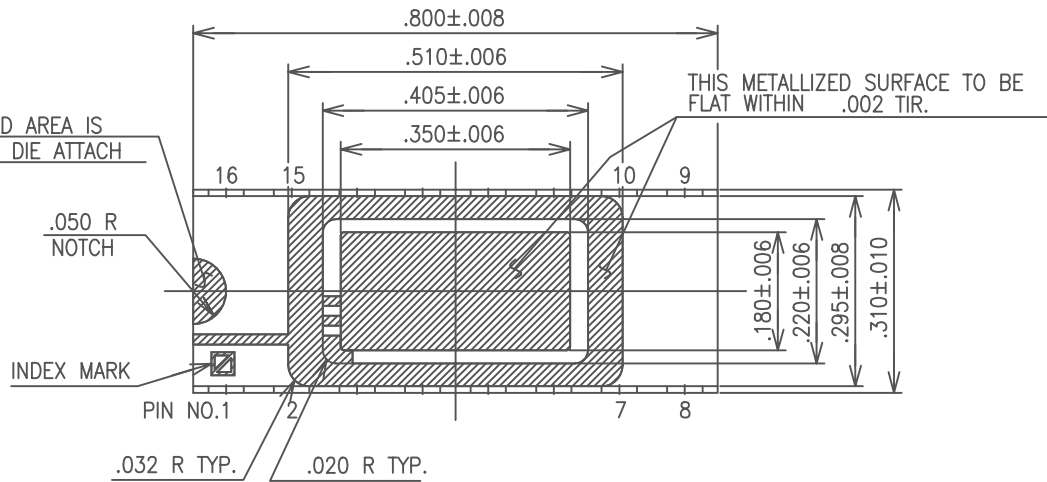


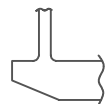
THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD



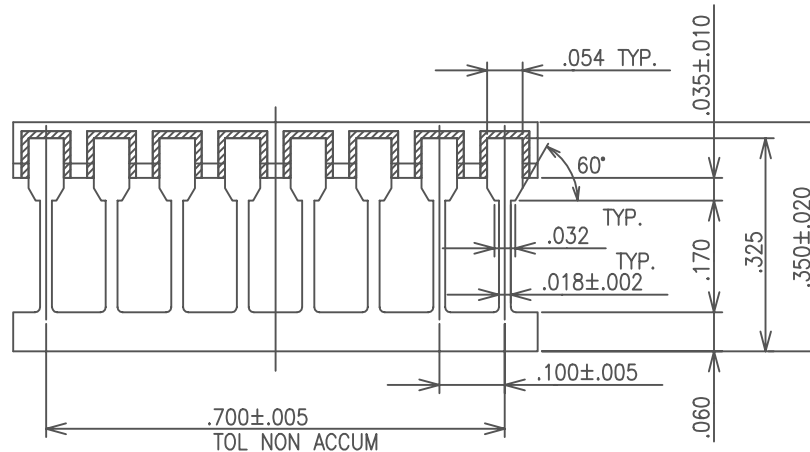
DETAIL-A

NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.20 OHMS MAX.



VENDOR'S OPTION



SB016L086-1 S=0 D=0

MODIFICATION						NAME 16 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION	DRAWN M.K	CHECKED AF/TA	APPROVED K.M	DATE JUL30'92
	SCALE 5/1	MATERIAL AS INDICATED	DRAWING NO. KD-81086-B				SHEET 1/2				
△ B	REDRAWN(CONVERTED CAD DATA) CHANGED	JUL8'98 DATE	M.SU DRAWN	SH.K/S.F CHECKED	T.A APPROVED	KYOCERA KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-81086-B		SHEET 1/2		

